

ABSTRACT

The present invention provides a method for producing an electronic device apparatus with which more suitable thermal conductivity of a resin sheet for sealing can be exhibited. Provided is a method for producing an electronic device apparatus, said method being provided with: a step (A) of preparing a laminate formed by fixing an electronic device to a support body; a step (B) of preparing a resin sheet for sealing, said resin sheet containing a secondary aggregate formed by aggregating thermally anisotropic boron nitride crystals, in which thermal conductivity differs depending on the direction, so as to be isotropic; a step (C) of disposing the resin sheet for sealing on the electronic device of the laminate; a step (D) of embedding the electronic device in the resin sheet for sealing; and a step (E), after step (D), of heating the resin sheet for sealing and subjecting said resin sheet to primary thermosetting while maintaining pressurization in a direction that brings the laminate and the resin sheet for sealing toward each other.